

TENTATIVE

TOSHIBA GATE TURN-OFF THYRISTOR

## SG3000GXH25

INVERTER APPLICATION

Unit in mm

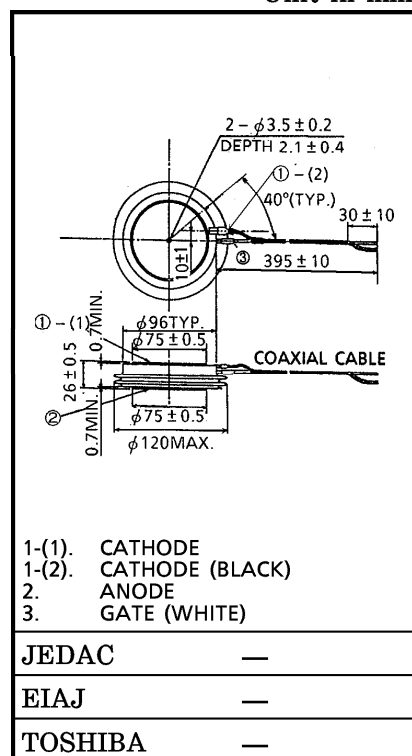
- Repetitive Peak Off-State Voltage :  $V_{DRM} = 4500\text{ V}$   
(Note 1)
- Repetitive Peak Reverse Voltage :  $V_{RRM} = 4000\text{ V}$
- R.M.S On-State Current :  $I_T(\text{RMS}) = 800\text{ A}$
- Peak Turn-Off Current :  $I_{TGQM} = 3000\text{ A}$
- Critical Rate of Rise of On-State Current :  $di/dt = 300\text{ A}/\mu\text{s}$
- Critical Rate of Rise of Off-State Voltage :  $dv/dt = 900\text{ V}/\mu\text{s}$

## MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Off-State Voltage (Note 1)	$V_{DRM}$	4500	V
Repetitive Peak Reverse Voltage	$V_{RRM}$	4000	V
Peak Turn-Off Current (Note 2)	$I_{TGQM}$	3000	A
R.M.S On-State Current (Note 3)	$I_T(\text{RMS})$	800	A
Peak One Cycle Surge On-State Current (Non Repetitive, 10 ms- Width Half Sine Waveform)	$I_{TSM}$	16000	A
Critical Rate of Rise of On-State Current (Note 4)	$di/dt$	300	A / $\mu\text{s}$
Peak Forward Gate Current	$I_{FGM}$	100	A
Average Gate Power Dissipation	$P_G(\text{AV})$	150	W
R.M.S Gate Current (Note 5)	$I_G(\text{RMS})$	42	A
Peak Reverse Gate Voltage (At Static)	$V_{RGM}$	16	V
Operation Junction Temperature Range	$T_j$	-40~115	°C
Storage Temperature Range	$T_{stg}$	-40~115	°C
Mounting Force	—	$33.3 \pm 4.9$	kN

(Note 1) :  $V_{GK} = -2\text{ V}$ (Note 2) :  $V_D = 2400\text{ V}$ ,  $V_{DM} \leq 3000\text{ V}$ ,  $C_S \geq 6\text{ }\mu\text{F}$ ,  $di_{GQ}/dt \geq 40\text{ A}/\mu\text{s}$ ,  $V_{DSP} \leq 800\text{ V}$ ,  
 $L_S \leq 0.2\text{ }\mu\text{H}$  (TOSHIBA METHOD)

(Note 3) : 50 Hz Half Sine Waveform

(Note 4) :  $V_D \leq 2400\text{ V}$ ,  $I_{TM} \leq 3000\text{ A}$ ,  $I_G \geq 30\text{ A}$  ( $t_r \leq 1\text{ }\mu\text{s}$ ),  $f \leq 50\text{ Hz}$ ,  $C_S \leq 6\text{ }\mu\text{F}$ ,  
 $R_S \geq 10\text{ }\Omega$ ,  $25^\circ\text{C} \leq T_j \leq 115^\circ\text{C}$ (Note 5) : Ambient Temperature of coaxial gate-cathode lead =  $90^\circ\text{C}$ 

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## ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Repetitive Peak Off-State Current	$I_{DRM}$	$V_{DRM} = 4500\text{ V}$ , $V_{GK} = -2\text{ V}$ $T_j = 115^\circ\text{C}$	—	—	150	mA
Repetitive Peak Reverse Current	$I_{RRM}$	$V_{RRM} = 4000\text{ V}$ $T_j = 115^\circ\text{C}$	—	—	150	mA
Repetitive Peak Reverse Gate Current	$I_{RGM}$	$V_{RGM} = 16\text{ V}$ $T_j = 115^\circ\text{C}$	—	—	10	mA
Peak On-State Voltage	$V_{TM}$	$I_{TM} = 2500\text{ A}$ , $T_j = 115^\circ\text{C}$	—	—	4.6	V
Gate Trigger Voltage	$V_{GT}$	$V_D = 24\text{ V}$ $R_L = 0.1\ \Omega$	$T_j = -40^\circ\text{C}$	—	2.5	V
			$T_j = 25^\circ\text{C}$	—	1.5	V
Gate Trigger Current	$I_{GT}$		$T_j = 0^\circ\text{C}$	—	8.5	A
			$T_j = 25^\circ\text{C}$	—	2.5	A
Turn-On Delay Time	$t_d$	$V_D = 2250\text{ V}$ , $I_{TM} = 2500\text{ A}$ $di_F/dt = 300\text{ A}/\mu\text{s}$	—	—	3.0	$\mu\text{s}$
Turn-On Time	$t_{gt}$	$I_{GM} = 30\text{ A}$ ( $t_r = 1\ \mu\text{s}$ ) $T_j = 25^\circ\text{C}$ , non-snubber	—	—	15	$\mu\text{s}$
Critical Rate of Rise of Off-State Voltage	$dv/dt$	$V_{DRM} = 3000\text{ V}$ $T_j = 115^\circ\text{C}$ , $V_{GK} = -4\text{ V}$ Exponential Rise	900	—	—	$\text{V}/\mu\text{s}$
Storage Time	$t_s$	$I_{TGQ} = 2500\text{ A}$	—	—	20	$\mu\text{s}$
Gate Turn-Off Time	$t_{gq}$	$V_{DM} = 3000\text{ V}$ , $T_j = 115^\circ\text{C}$	—	—	22	$\mu\text{s}$
Tail Time	$t_{tail}$	$V_D = 2250\text{ V}$ , $C_S = 6\ \mu\text{F}$ $di_{GQ}/dt = 50\text{ A}/\mu\text{s}$	—	—	250	$\mu\text{s}$
Gate Turn-Off Current	$I_{GQ}$	Off squeeze current $\geq 300\text{ mA}$	—	—	750	A
Reverse Recovery Charge	$Q_{rr}$	$I_T = 3000\text{ A}$ , $V_R = 1500\text{ V}$ $C_S = 6\ \mu\text{F}$ , $R_S = 5\ \Omega$	—	—	4800	$\mu\text{C}$
Reverse Recovery Current	$t_{rr}$	$di_T/dt = -300\text{ A}/\mu\text{s}$ $T_j = 115^\circ\text{C}$	—	—	10	$\mu\text{s}$
Thermal Resistance	$R_{th(j-f)}$	Junction to fin	—	—	0.014	$^\circ\text{C}/\text{W}$

